

## Soldered SAM on **water** cooled copper heat sink with **25.0** mm diameter SAM- $\lambda$ -A-4.0-25.0w

SAM chip area            standard:        4.0 mm x 4.0 mm  
 Chip thickness           standard:        450  $\mu$ m  
 Front side protection    the SAM is protected with a dielectric front layer.

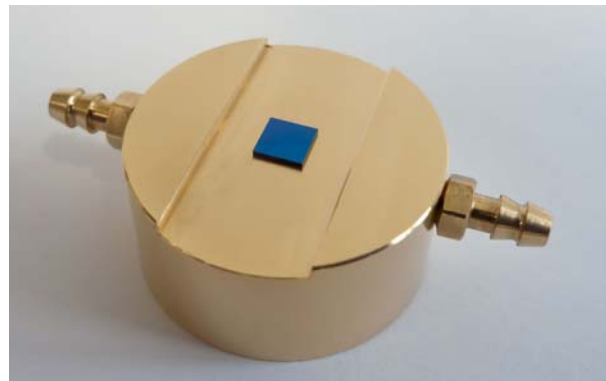
The SAM chip is soldered on a gold plated, water cooled copper mount with 25.0 mm diameter using a Sn/Bi solder. The solder provides a low thermal resistance between the SAM chip and the mount.

- The **standard** mounting position of the SAM is at the center of the heat sink.
- **Optional** the SAM can be soldered on the edge of the heat sink without extra charges.

Edge mounted: SAM- $\lambda$ -A-4.0-25.0w-e



Centre mounted: SAM- $\lambda$ -A-4.0-25.0w-c



Back side



This water cooled heat sink comes with a 2 m long water tube with an inner diameter of 3 mm.

### Recommended values for cooling water

flow rate:                    1000 cm<sup>3</sup>/h = 17 cm<sup>3</sup>/min  
 pressure difference        0.03 bar  
 maximum pressure        1 bar

